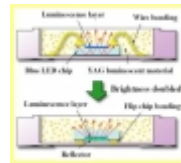


ASIA E-cots Pte Ltd

Asia Ecots

Gold to Gold Interconnection Ultrasonic Flip Chip Bonding (GGI)

Price per Unit (piece): [Call for Pricing](#)



Gold to Gold Interconnection Ultrasonic Flip Chip Bonding (GGI)

AFM-15 (Gold to gold ultrasonic process) *Upgraded*



Features

1. **Excellent mounting accuracy in the industry ($\pm 8\mu\text{m} / 3\sigma$)**
2. Excellent mounting cycle time in the industry (1.1 sec/IC, including processing time)
3. Low energy connection
4. Max 5mmIC Handling
5. Various functions for actual production

AFM-22 (Ultra low cost and space saving)



Features

1. Max 30mmIC Handling
2. Excellent mounting accuracy in the industry ($\pm 2 \mu\text{m} / 3\sigma$)
3. Capable of Max Load 372.4N (* Available for low pressure capability equipment)

AFM-12 (Gold-gold ultrasonic process)

Features

- 1. The highest mounting accuracy in the industry ($\pm 10\mu\text{m}$)**
- 2. Mounting cycle time of 1.5/IC (excluding bonding time)**
- 3. Lowest floor space required in the industry (1.1m^2)**

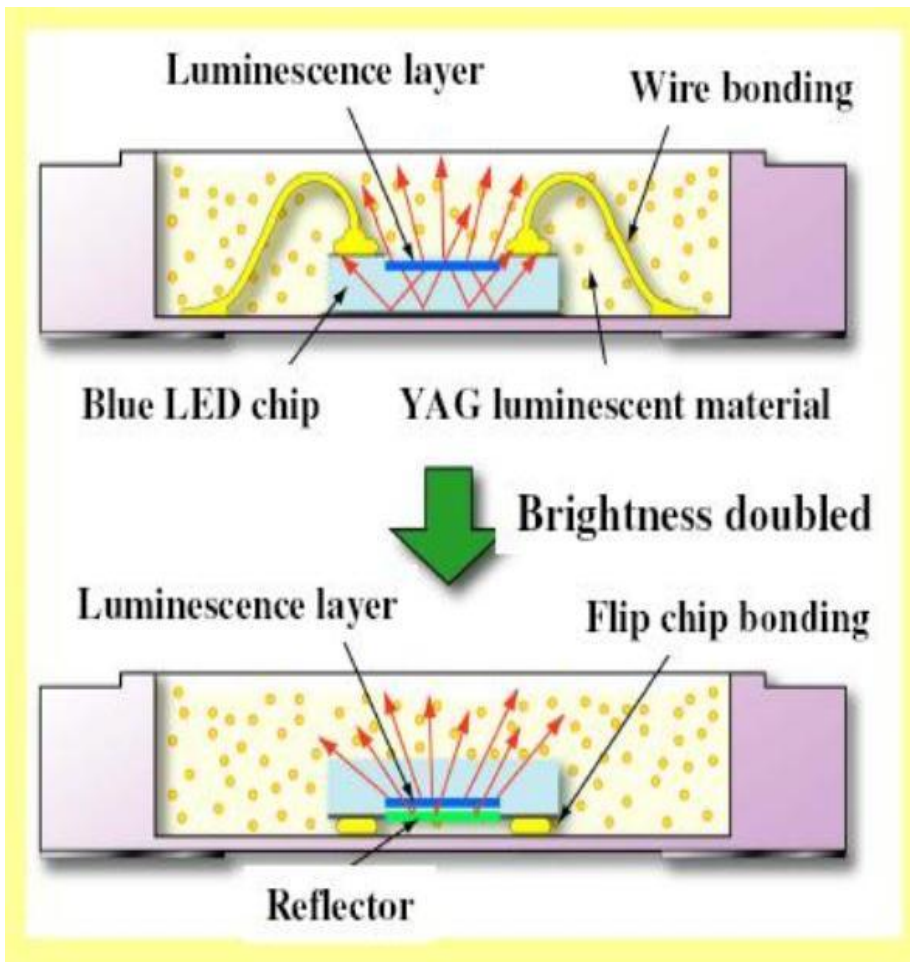
MDM-20 (Debut of multi-dispenser)



Features

- 1. High-precision coating by newly-developed image processor.**
- 2. Fine dispensing control by newly-developed processor.**
- 3. The new best space saving in the industry**

Gold-to-Gold Flip Chip Example: High Density LED



[Vendor Information](#)

Customer Reviews: There are yet no reviews for this product.
Please log in to write a review.